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FEEDING EQUIPMENT
DIE EJECT UNIT WITH SINGLE WAFER CHANGER AND NVS CHANGER

SKU: S3-0097.04
114.000,00 € **excl. VAT**

Categories: Feeding equipment, Modules

BESCHREIBUNG

The wafer system consisting of Die Eject Unit, Single Wafer Changer and Needle Vacuum System Changer is used to load wafers and to release components from the wafer foil to make them available to the machine for further processing. The components fixed on the wafer foil are released with a Needle Vacuum System and thus separated.

The Wafer Changer is used to feed a wafer to be processed and to remove the processed wafer. An integrated magazine enables to provide automatically up to 25 wafers with a size of 4” to 8” alternately one after the other.

The wafers are fed in without opening the doors of the machine.

The Wafer Changer is equipped with a laser safety window, which allows the wafer system to be used in machines with laser applications.

The integrated NVS Changer enables the needle vacuum systems to be changed automatically during the machining process. The changer offers space for up to 3 needle vacuum systems, which means that the entire system can work with 3 needle vacuum systems.

MORE INFORMATIONS

Dimensions in mm (W x D x H)	428,5 x 945,5 x 439,5

Max. wafer size in inch / mm	8 / 200
Voltage in V	24
Max. current in A	5
Communication interface	Ethernet , UNICAN